

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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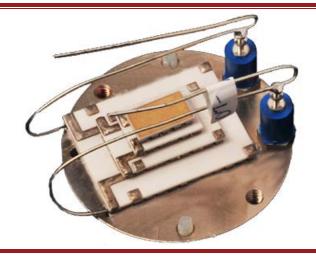






Technical Data Sheet for SP2394

Multi-Stage Thermoelectric Module



NOMINAL PERFORMANCE IN NITROGEN

Hot Side Temperature (°C)	27	50
Δ Tmax (°C):	130	146
Qmax (watts):	4.5	4.9
Imax (amps):	5.1	5.1
Vmax (vdc):	8.5	9.4
AC Resistance (ohms):	1.56	

PRODUCT FEATURES

- Pretinned metallized ceramic surface(s) with 117°C solder available.
- Elevated temperature burn-in with test data provide.
- Ceramic Material: Aluminum Oxide and Beryllium Oxide.

ORDERING OPTIONS

Model Number	Description
SP2394-01AB	Metallized Base and Top – cooler is
	mounted and shipped on test base
SP2394-02AB	Metallized Base Only – cooler is mounted
	and shipped on test base
SP2394-03AB	No Metallization, No Burn In
SP2394-04AB	Metallized Base Only, No Burn In
SP2394-05AB	Metallized Base and Top, 117° both sides
SP2394-07AB	Metallized Base and Top. No Burn In

OPERATION CAUTIONS

For maximum reliability, storage and operation below 85°C in a non-condensing environment is recommended. To minimize thermal stress, use linear/proportional temperature control or a similar method rather than an ON/OFF method.

INSTALLATION

Recommended mounting methods: Bonding with thermal epoxy or soldering with metallized ceramics. For additional information, please refer to our TEM Installation Guide.

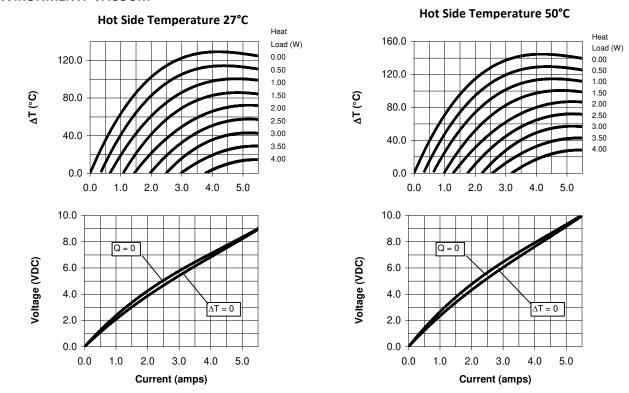
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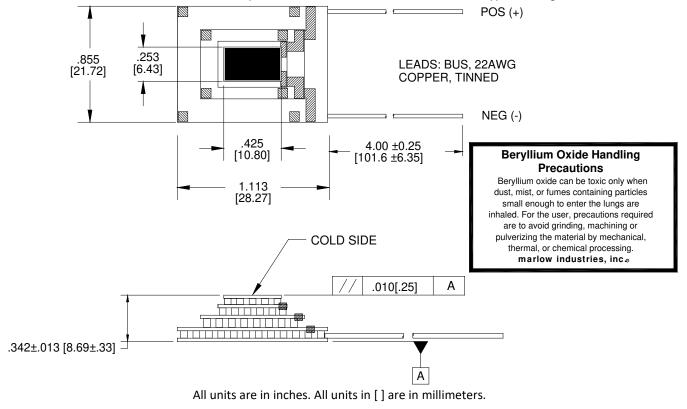
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ENVIRONMENT: VACUUM



For performance information in a vacuum or with hot side temperatures other than 27°C or 50°C, contact one of our Applications Engineers at 877-627-5691.



For customer support or general questions please contact a local office or visit our website at www.marlow.com.

Marlow reserves the right to make product changes without notice.